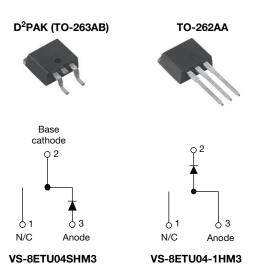


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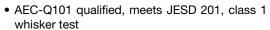
Ultrafast Rectifier, 8 A FRED Pt®



PRIMARY CHARACTERISTICS							
I _{F(AV)}	8 A						
V _R	400 V						
V _F at I _F	0.94 V						
t _{rr} typ.	35 ns						
T _J max.	175 °C						
Package	D ² PAK (TO-263AB), TO-262AA						
Circuit configuration	Single						

FEATURES

- Ultrafast recovery time
- Low forward voltage drop
- Low leakage current
- 175 °C operating junction temperature
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C



 Material categorization: for definitions of compliance please see www.vishay.com/doc?99912





DESCRIPTION / APPLICATIONS

Vishay Semiconductors FRED Pt® series are the state of the art ultrafast recovery rectifiers specifically designed with optimized performance of forward voltage drop and ultrafast recovery time.

The planar structure and the platinum doped life time control, guarantee the best overall performance, ruggedness and reliability characteristics.

These devices are intended for use in the output rectification stage of SMPS, UPS, DC/DC converters as well as freewheeling diode in low voltage inverters and chopper motor drives.

Their extremely optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

ABSOLUTE MAXIMUM RATINGS									
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS					
Repetitive peak reverse voltage	V_{RRM}		400	V					
Average rectified forward current	I _{F(AV)}	T _C = 155 °C	8						
Non-repetitive peak surge current	I _{FSM}	T _C = 25 °C	100	Α					
Repetitive peak forward current	I _{FRM}		16						
Operating junction and storage temperatures	T _J , T _{Stg}		-55 to +175	°C					

ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified)									
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS			
Breakdown voltage, blocking voltage	V _{BR} , V _R	Ι _R = 100 μΑ	400	-	-				
Forward voltage	V _F	I _F = 8 A	-	1.19	1.3	V			
Forward voitage		I _F = 8 A, T _J = 150 °C	-	0.94	1.0				
Devenue legicare august	I _R	V _R = V _R rated	-	0.2	10				
Reverse leakage current		T _J = 150 °C, V _R = V _R rated	-	20	500	μA			
Junction capacitance	C _T	V _R = 400 V	-	14	-	pF			
Series inductance	L _S	Measured lead to lead 5 mm from package body	-	8.0	-	nH			

VS-8ETU04SHM3, VS-8ETU04-1HM3

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DYNAMIC RECOVERY CHARACTERISTICS (T _J = 25 °C unless otherwise specified)								
PARAMETER	SYMBOL	TEST CO	TEST CONDITIONS			MAX.	UNITS	
		$I_F = 1.0 \text{ A}, dI_F/dt =$	= 50 A/μs, V _R = 30 V	-	35	60		
Reverse recovery time	t _{rr}	T _J = 25 °C		-	43	-	ns	
		T _J = 125 °C		-	67	-		
Dook received ourrent	I _{RRM}	T _J = 25 °C	I _F = 8 A dI _F /dt = 200 A/µs V _R = 200 V	-	2.8	-	Α	
Peak recovery current		T _J = 125 °C		-	6.3	-		
Poverse receivery charge	Q _{rr}	T _J = 25 °C		-	60	-	200	
Reverse recovery charge		T _J = 125 °C		-	210	-	nC	

THERMAL - MECHANICAL SPECIFICATIONS									
PARAMETER	ARAMETER SYMBOL TEST CONDITIONS				MAX.	UNITS			
Maximum junction and storage temperature range	T _J , T _{Stg}		-55	-	175	°C			
Thermal resistance, junction to case	R _{thJC}		-	1.8	2.0				
Thermal resistance, junction to ambient	R _{thJA}	Typical socket mount	-	-	50	°C/W			
Thermal resistance, case to heatsink	R _{thCS}	Mounting surface, flat, smooth, and greased	-	0.5	-				
Weight			-	2.0	-	g			
vveigni			-	0.07	-	oz.			
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)			
Moulting device		Case style D ² PAK (TO-263AB)		8ETU04SH					
Marking device		Case style TO-262	8ETU04-1H						

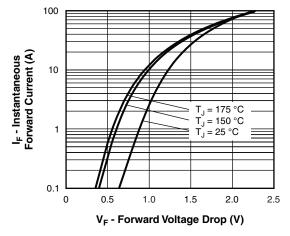


Fig. 1 - Typical Forward Voltage Drop Characteristics

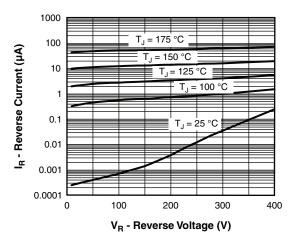


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

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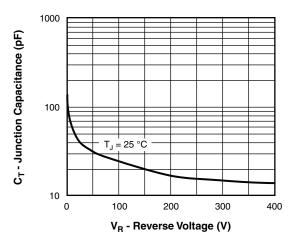


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

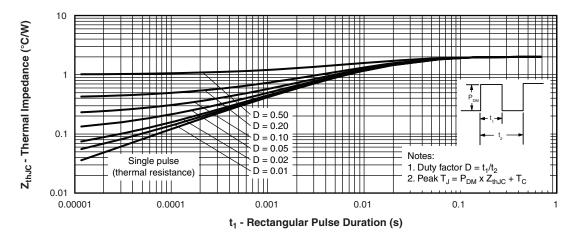


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics

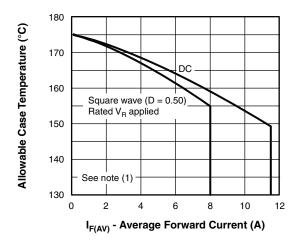


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

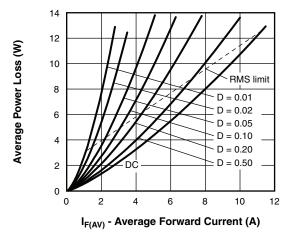


Fig. 6 - Forward Power Loss Characteristics



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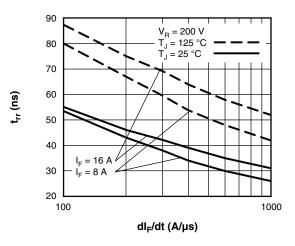


Fig. 7 - Typical Reverse Recovery Time vs. dl_F/dt

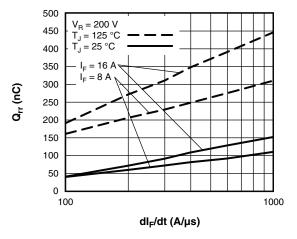
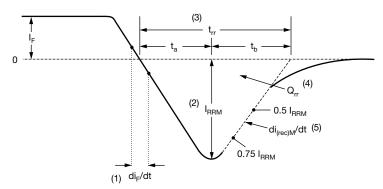


Fig. 8 - Typical Stored Charge vs. dl_F/dt

Note

 $^{(1)}$ Formula used: T_C = T_J - (Pd + Pd_{REV}) x R_{thJC}; Pd = forward power loss = I_{F(AV)} x V_{FM} at (I_{F(AV)}/D) (see fig. 6); Pd_{REV} = inverse power loss = V_{R1} x I_R (1 - D); I_R at V_{R1} = rated V_R



- (1) di_F/dt rate of change of current through zero crossing
- (2) I_{RRM} peak reverse recovery current
- (3) $\rm t_{rr}$ reverse recovery time measured from zero crossing point of negative going $\rm I_F$ to point where a line passing through 0.75 $\rm I_{RRM}$ and 0.50 $\rm I_{RRM}$ extrapolated to zero current.
- (4) Q_{rr} area under curve defined by t_{rr} and I_{RRM}

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

(5) $di_{(rec)M}/dt$ - peak rate of change of current during t_b portion of t_{rr}

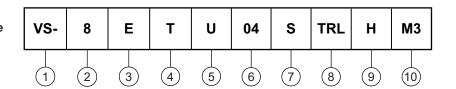
Fig. 9 - Reverse Recovery Waveform and Definitions

VS-8ETU04SHM3, VS-8ETU04-1HM3

Vishay Semiconductors

ORDERING INFORMATION TABLE

Device code



Vishay Semiconductors product

2 - Current rating (8 A)

E = single diode

T = TO-220, D²PAK

5 - U = ultrafast recovery

Voltage rating (04 = 400 V)

7 - • $S = D^2PAK$

• -1 = TO-262

None = tube (50 pieces)

• TRL = tape and reel (left oriented, for D²PAK package)

• TRR = tape and reel (right oriented, for D²PAK package)

9 - H = AEC-Q101 qualified

- M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free

ORDERING INFORMATION (Example)							
PREFERRED P/N	BASE QUANTITY	PACKAGING DESCRIPTION					
VS-8ETU04SHM3	50	Antistatic plastic tube					
VS-8ETU04STRRHM3	800	13"diameter reel					
VS-8ETU04STRLHM3	800	13"diameter plastic reel					
VS-8ETU04-1HM3	50	Antistatic plastic tube					

LINKS TO RELATED DOCUMENTS						
Dimensions	D ² PAK (TO-263AB)	www.vishay.com/doc?95046				
Differsions	TO-262AA	www.vishay.com/doc?95419				
Doub according information	D ² PAK (TO-263AB)	www.vishay.com/doc?95444				
Part marking information	TO-262AA	www.vishay.com/doc?95443				
Packaging information	D ² PAK (TO-263AB)	www.vishay.com/doc?95032				



Vishay Semiconductors

D²PAK

DIMENSIONS in millimeters and inches



SYMBOL	MILLIMETERS		INC	INCHES		NOTES SYMBOL MILLIMETERS INCHES	SYMPOL MILLIMETERS INC	MILLIMETERS		HES	NOTES	
STIVIBUL	MIN.	MAX.	MIN.	MAX.	NOTES	NOIES	STIVIBUL	MIN.	MAX.	MIN.	MAX.	NOTES
Α	4.06	4.83	0.160	0.190			D1	6.86	8.00	0.270	0.315	3
A1	0.00	0.254	0.000	0.010			Е	9.65	10.67	0.380	0.420	2, 3
b	0.51	0.99	0.020	0.039			E1	7.90	8.80	0.311	0.346	3
b1	0.51	0.89	0.020	0.035	4		е	2.54	BSC	0.100	BSC	
b2	1.14	1.78	0.045	0.070			Н	14.61	15.88	0.575	0.625	
b3	1.14	1.73	0.045	0.068	4		L	1.78	2.79	0.070	0.110	
С	0.38	0.74	0.015	0.029			L1	-	1.65	-	0.066	3
c1	0.38	0.58	0.015	0.023	4		L2	1.27	1.78	0.050	0.070	
c2	1.14	1.65	0.045	0.065			L3	0.25	BSC	0.010	BSC	
D	8.51	9.65	0.335	0.380	2		L4	4.78	5.28	0.188	0.208	

Notes

- (1) Dimensioning and tolerancing per ASME Y14.5 M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Datum A and B to be determined at datum plane H
- (6) Controlling dimension: inch
- (7) Outline conforms to JEDEC® outline TO-263AB

Vishay Semiconductors

TO-262

DIMENSIONS in millimeters and inches



SYMBOL	MILLIN	METERS	INC	INCHES			
STIVIBUL	MIN.	MAX.	MIN.	MAX.	NOTES		
Α	4.06	4.83	0.160	0.190			
A1	2.03	3.02	0.080	0.119			
b	0.51	0.99	0.020	0.039			
b1	0.51	0.89	0.020	0.035	4		
b2	1.14	1.78	0.045	0.070			
b3	1.14	1.73	0.045	0.068	4		
С	0.38	0.74	0.015	0.029			
c1	0.38	0.58	0.015	0.023	4		
c2	1.14	1.65	0.045	0.065			
D	8.51	9.65	0.335	0.380	2		
D1	6.86	8.00	0.270	0.315	3		
E	9.65	10.67	0.380	0.420	2, 3		
E1	7.90	8.80	0.311	0.346	3		
е	2.54 BSC		0.100	BSC			
L	13.46	14.10	0.530	0.555			
L1	-	1.65	-	0.065	3		
L2	3.36	3.71	0.132	0.146			

Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- 5) Controlling dimension: inches
- (6) Outline conform to JEDEC TO-262 except A1 (maximum), b (minimum), D1 (minimum) and L2 where dimensions derived the actual package outline

Revision: 11-Jul-2019 1 Document Number: 95419



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